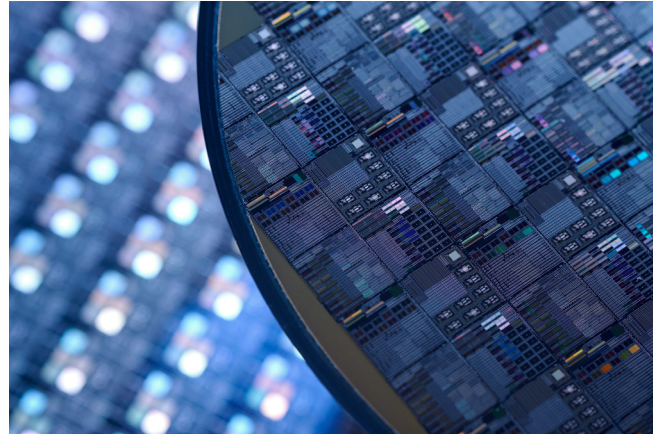


ALPHA[®] WS945CPS

WATER SOLUBLE FINE FEATURE AND HIGH ACTIVE SOLDER PASTE

ALPHA WS945CPS is a new Type 7 solder paste for the system in package (SiP) package market. The SiP market is growing and there is a need for better interconnected product performance as well as stronger EHS protections. In turn, this new product has key features to meet both of these expanding requirements.

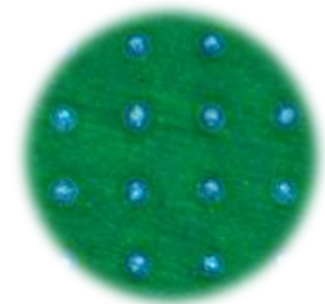


TARGET APPLICATION

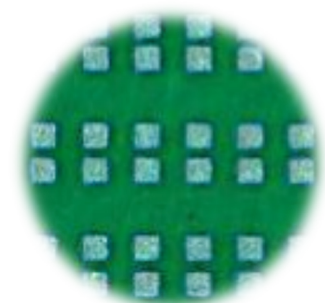
- WLCSP & component attachment on System in Package
- Small size opening and fine pitch semiconductor application
- MicroBump on wafer, panel or substrate

KEY PRODUCT FEATURES

- Water soluble & Halogen Free
- Supplying it by Type 6 & 7 powder
- Excellent print performance on <50um & AR0.5 opening
- Excellent performance by 008004 chip capacitor
- Good for Jetting, Dispensing and Printing
- Long stencil life on various environment
- Good on slump, bridge, tackiness, void
- Easy cleaning by DI water
- Min. bead and good wetting on various reflow process



Good Solder Paste print on
50um open (AR 0.50)



NO Solder Paste Bridge
with 40um gap



MacDermid Alpha
ELECTRONICS SOLUTIONS



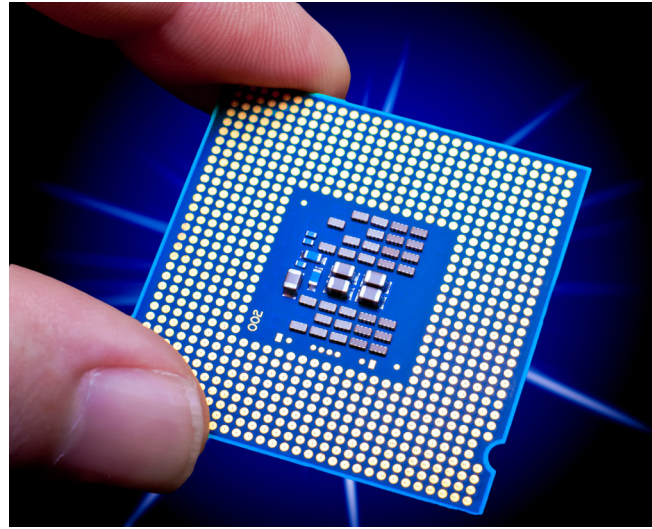
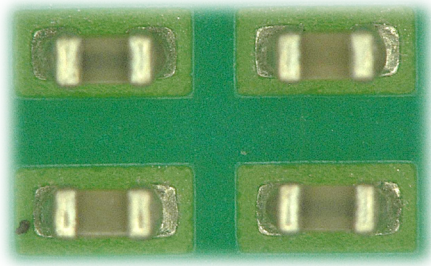
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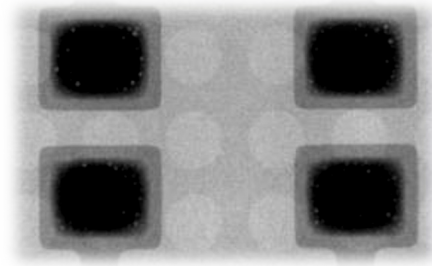
SUPERIOR PERFORMANCE

Performance is maximized as this product enhances SiP manufacturing by providing precise deposition for intricate, high-density component arrangements and maintaining performance with long stencil life.

Its superior properties, such as minimal slump and excellent tackiness, ensure reliable solder joints with reduced defects like voids, beads, and bridging, crucial for the compact and complex designs typical in SiP applications.



**Good wetting on 008004
component attachment**



**Good for void on 01005
component attachment**

This new paste is both water soluble and halogen free, two distinct measures that limits EHS risks in production. It supports the System in Package production by reducing the risk of harmful emissions and chemical exposure during manufacturing. Water-soluble solder paste simplifies cleaning and waste disposal, while halogen-free formulations minimize toxic byproducts, aligning with environmental regulations and improving workplace safety.

